

规格书编号

SPEC NO :

产品规格书

SPECIFICATION

CUSTOMER 客户: _____
PRODUCT 产品: _____ SAW FILTER _____
MODEL NO 型号: _____ HDF465AS F11A _____
PREPARED 编制: _____ CHECKED 审核: _____
APPROVED 批准: _____ DATE 日期: _____ 2006-5-11 _____

| | | |
|-------------------------|-------------|---------|
| 客户确认 CUSTOMER RECEIVED: | | |
| 审核 CHECKED | 批准 APPROVED | 日期 DATE |
| | | |

无锡市好达电子股份有限公司
Shoulder Electronics Limited

1. SCOPE

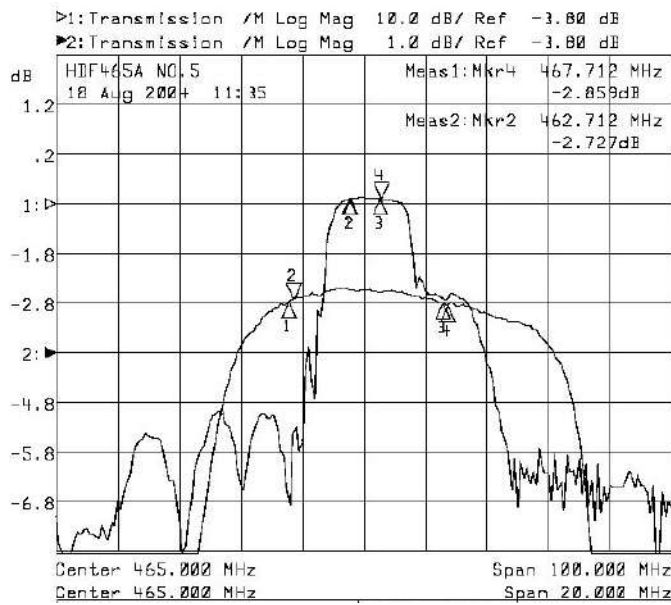
This specification shall cover the characteristics of SAW filter With 465M used for the page system.

2. ELECTRICAL SPECIFICATION

| | |
|-----------------------|----------------|
| DC Voltage VDC | 10V |
| AC Voltage Vpp | 10V50Hz/60Hz |
| Operation temperature | -20°C to +60°C |
| Storage temperature | -45°C to +85°C |
| RF Power Dissipation | 0dBm |

Electronic Characteristics

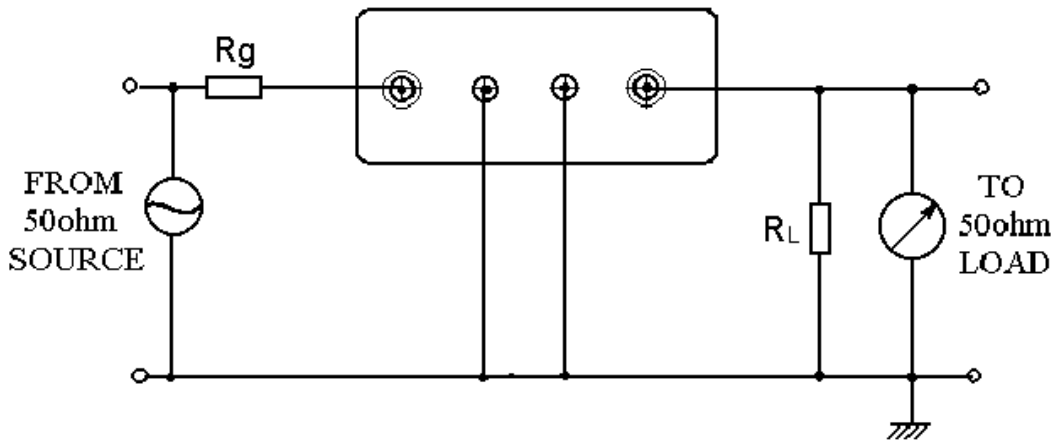
2-1. Typical frequency response



2-2. Electrical characteristics

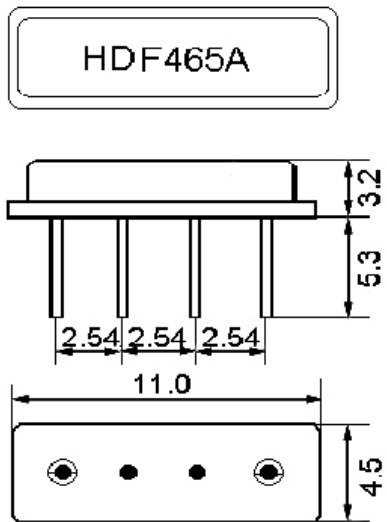
| Item | Frequency(MHz) | Specification |
|------------------------|----------------------------------|-------------------------|
| Center Frequency(Fo) | 465.00 | |
| Passband Width | Fo±3.0 | |
| Insertion Loss | Passband | 4.0 dB max. |
| Ripple Deviation | Passband | 1.5 dB max. |
| Stop band Suppression | Fo-100~Fo-40.8 Fo+40.8-Fo+100 | 55dB min. 55 dB min. |
| Input/output Impedance | | 50Ω//0pF |

3. TEST CIRCUIT

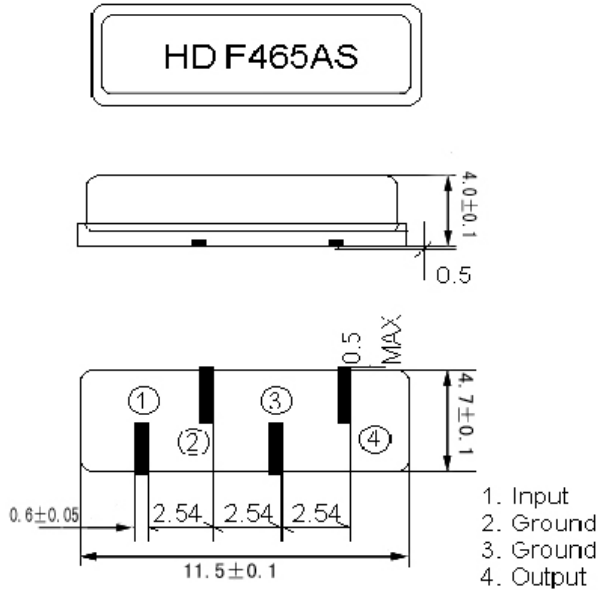


4. DIMENSION

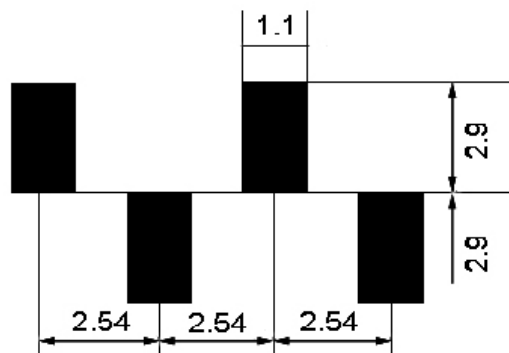
■ DIP TYPE:



■ SEMI-SMD TYPE:



■ Recommended layout of PCB(MM) (Tolerance ± 0.2MM)



5. ENVIRONMENTAL CHARACTERISTICS

5-1 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of $+25^{\circ}\text{C}$ for 5 Minutes and a higher temperature of $+85^{\circ}\text{C}$ for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in table 1.

5-2 Resistance to solder heat

Submerge the device terminals into the solder bath at $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in table 1.

5-3 Solderability

Submerge the device terminals into the solder bath at $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in table 1.

5-4 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the filter shall fulfill the specifications in table 1.

5-5 Vibration

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The filter shall fulfill the specifications in table 1.

6. REMARK

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.